## **AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application:

## **Listing of Claims**

- 1. (Currently amended) A touch panel, comprising:
  - an upper electrode plate;
  - a lower electrode plate being isolated electrically with said upper electrode plate;
- a plurality of <u>first</u> conductive lines connected electrically to said upper electrode plate and said lower electrode plate respectively; <del>and</del>
  - a terminal area, parts of said plurality of first conductive lines located on said terminal area;
- a flexible printed circuit board (FPC) connected electrically to [[a]] <u>said</u> terminal area <u>of said</u> touch panel, parts of said plurality of conductive lines located on said terminal area, wherein the folded parts of said FPC are overlapped over said touch panel, said FPC comprising a folded part folded to overlap at least a portion of the remainder of the touch panel; and
- a plurality of second conductive lines located on said folded part of said FPC, said plurality of second conductive lines electrically connected to said plurality of first conductive lines.
- 2. (Original) The touch panel according to claim 1, further comprising a second FPC connected electrically to said touch panel.
- 3. (Currently amended) The touch panel according to claim 1, wherein said plurality of conductive lines are the silver lines.
- 4. (Original) The touch panel according to claim 1, wherein said FPC is connected electrically to said touch panel by the bonding method.
- 5. (Original) The touch panel according to claim 1, further comprising a plurality of dot spacers located in between said upper electrode plate and said lower electrode plate.

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6. (Original) The touch panel according to claim 1, further comprising an adhesion layer disposed between said upper electrode plate and said lower electrode plate to adhere said

upper and lower electrode plate.

7. (Original) The touch panel according to claim 1, wherein said upper electrode plate includes a first base substrate and an upper conductive layer formed beneath said first base substrate, and

said lower electrode plate includes a second base substrate and a lower conductive layer

formed on said second base substrate.

8. (Currently amended) A touch panel comprising:

a first electrode plate;

a second electrode plate being isolated electrically with said first electrode plate wherein said

first electrode plate and second electroplate together define at least one edge;

a plurality of first conductive lines connected electrically to said first electrode plate and said

second electrode plate respectively; and

a flexible printed circuit board (FPC) connected electrically to said edge a terminal area of

said touch panel by the bonding method, said FPC comprising a folded part folded to overlap at

least a portion of the remainder of the touch panel; and

a plurality of at least one second conductive lines line located on said folder part of said FPC

and connected electrically with at least one of said plurality of first conductive lines, wherein the

folded parts of said FPC are overlapped over said touch panel.

9. (Currently amended) The touch panel according to claim 8, wherein said plurality of first

conductive lines and said plurality of second conductive lines line are the silver lines.

10. (Original) The touch panel according to claim 8, further comprising an adhesion layer

disposed between said first electrode plate and said second electrode plate to adhere said first

and second electrode plate.

11. (Original) The touch panel according to claim 8, wherein said first electrode plate includes a

first base substrate and a first conductive layer formed on said first base substrate, and said

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second electrode plate includes a second base substrate and a second conductive layer formed on said second base substrate.

- 12. (Original) The touch panel according to claim 8, further comprising a second FPC connected electrically to said touch panel.
- 13. (Original) The touch panel according to claim 8, further comprising a plurality of dot spacers located in between said first electrode plate and said second electrode plate.
- 14. (New) A touch panel, comprising:
  - an upper electrode plate;
  - a lower electrode plate being isolated electrically with said upper electrode plate;
  - a surrounding area;
- a plurality of conductive lines located on said surrounding area and connected electrically to said upper electrode plate and said lower electrode plate respectively;
- a flexible printed circuit board (FPC) connected to the surrounding area, said FPC comprising a folded part folded to overlap at least a portion of the remainder of the touch panel, wherein a part of at least one of said plurality of conductive lines is located on said folded part.
- 15. (New) The touch panel according to claim 14, further comprising a second FPC connected electrically to said touch panel.
- 16. (New) The touch panel according to claim 14, wherein said plurality of conductive lines are the silver lines.
- 17. (New) The touch panel according to claim 14, wherein said FPC is connected electrically to said touch panel by the bonding method.
- 18. (New) The touch panel according to claim 14, further comprising a plurality of dot spacers located in between said upper electrode plate and said lower electrode plate.

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19. (New) The touch panel according to claim 14, further comprising an adhesion layer disposed between said upper electrode plate and said lower electrode plate to adhere said upper and lower electrode plate.

20. (New) The touch panel according to claim 14, wherein said upper electrode plate includes a first base substrate and an upper conductive layer formed beneath said first base substrate, and said lower electrode plate includes a second base substrate and a lower conductive layer formed on said second base substrate.